FORESEE DDR4 SO-DIMM
2666 Datasheet

Version: 1.0

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Revision History

Revision No.	History	Draft Date	Remark
1.0	Release	Dec 2019	

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1. Type

ECC DDR4 SO-DIMM 260PIN

2. Full conception

DDR4 SDRAM Unbuffered DIMM, It supports 1.2V low voltage mode. Design 260PIN golden finger interface protocols, and it supports two dual channel applications.

3. Design refer

JEDEC ECC DDR4 R/C

4. Product Name

Industrial Memory

5. Capacity information

DDR4 8GB/16GB

6. Book Sheet

Type	Capacity	Speed	HV P/N
ECC SO-DIMM	8 GB	2666	FD4AX2666C8GSC
ECC SO-DIMM	16 GB	2666	FD4AX2666CQGSC

7. Specification

Specification	JEDEC ECC DDR4 Reference
Interface	DDR4 260PIN SO-DIMM
Capacity	8/16/GB
Speed	2666Mbps
CAS Latency	19
Organization	1/2 Rank x8
Voltage	1.2V
Operating Temp.	0~85℃ (Surface)
Storage Temp.	-40℃ ~ +85℃
Form Factor	69.6 * 30 mm
Application	Industrial（general reference）

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8. PCB Specifications

General

1. Board size：69.6 x 30 mm ± 0.15 mm
2. Thickness：1.2 ± 0.1 mm
3. Pin count：260 PIN

PCB Material

1. RoHS
2. Glass Epoxy FR4, .UL 94V-0

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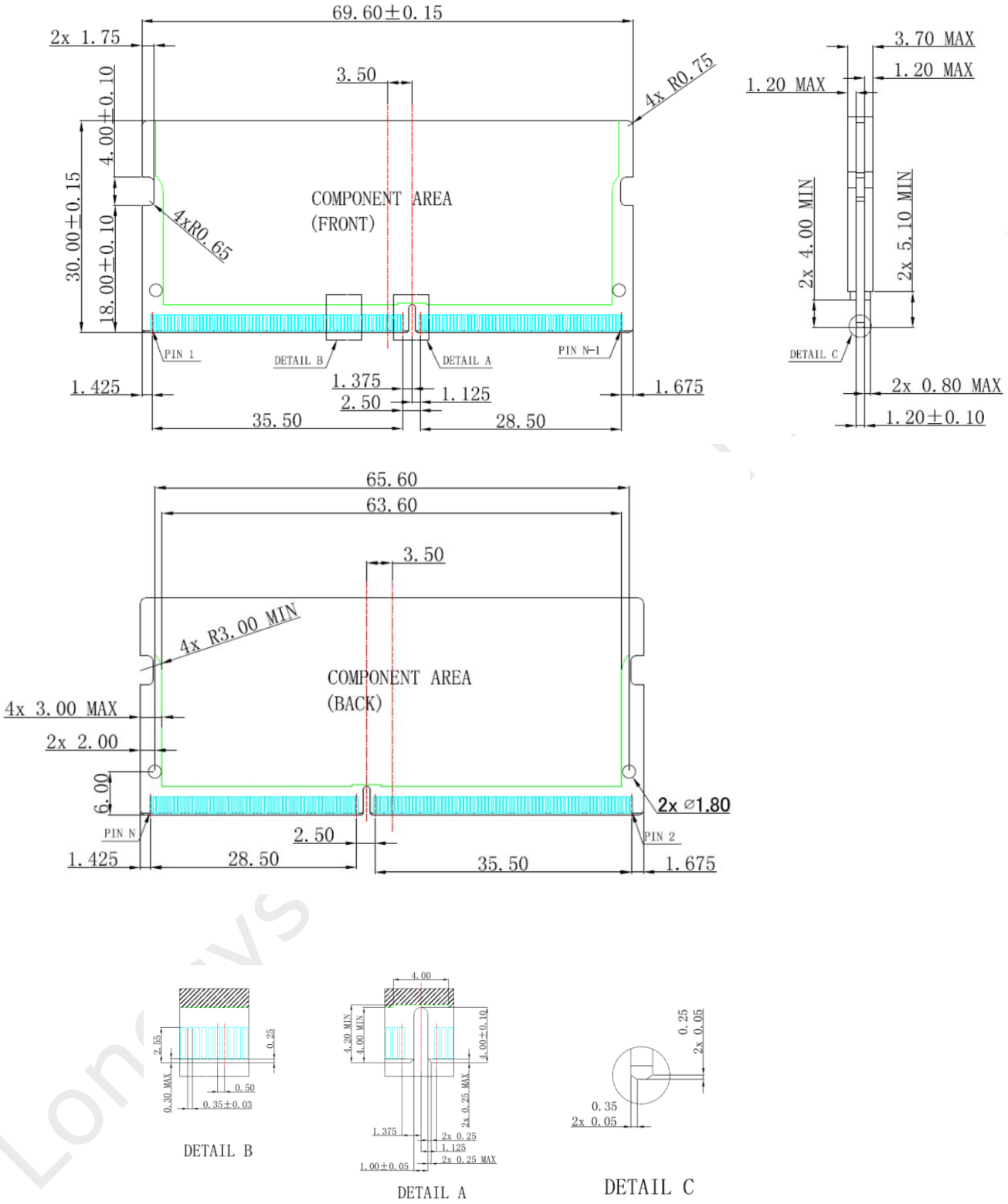
9. Module Dimensions



Units: millimeters